IN THE CLAIMS:

Please cancel claims 5-7, 10, 12, 16, 22, and 53-58, and amend the claims as follows:

1. (Previously Presented) An apparatus for supporting a substrate in a chamber having at least one substrate support member coupled to the chamber, comprising:

a body having a first portion and a second portion, the first portion adapted to interface with the support member;

a socket disposed in the second portion and having a ball support surface; and

a ball rotatably disposed on the ball support surface in the socket, wherein the ball is at least one of coated or plated, the ball adapted to contact and support a substrate thereon.

2. (Previously Presented) The apparatus of claim 1, wherein the ball has a surface roughness of 4 micro-inches or smoother.

3. (Original) The apparatus of claim 1, wherein the ball is coated or plated with chromium, an aluminum alloy, silicon nitride, or tungsten nitride.

4. (Original) The apparatus of claim 1, wherein the ball support surface has a radius greater than a radius of the ball.

5-7. (Cancelled)

8. (Currently Amended) An apparatus for supporting a glass substrate, comprising:

a chamber body having at least one substrate access port;

at least one support member disposed in the chamber body; ~~and~~

a socket disposed in the support member and having a ball support surface; and

one or more balls disposed on ~~a first side of the support member~~ the ball support surface in the socket, the balls rotatably adapted to support the glass substrate in a spaced-apart relation to the support member.

9. (Original) The apparatus of claim 8 further comprising:

a spacer having a first portion and a second portion, the first portion disposed on the support member and the second portion having a socket that rotatably retains the ball therein.

10. (Canceled)

11. (Original) The apparatus of claim 10, wherein the ball support further comprises:

a curved surface having a single contact point with the ball.

12. (Cancelled)

13. (Original) The apparatus of claim 10, wherein the ball support centers the ball within the socket.

14. (Original) The apparatus of claim 8, wherein the ball has a surface roughness of 4 micro-inches or smoother.

15. (Original) The apparatus of claim 9 further comprising:

a plurality of mounting pins coupled to the support member, each pin coupled to a respective spacer.

16. (Cancelled)

17. (Original) The apparatus of claim 8, wherein at least one of the balls is positioned to support a center portion of the substrate.

18. (Original) The apparatus of claim 8, wherein some of the balls support a perimeter portion of the substrate and at least one of the balls is positioned to support a center portion of the substrate.

19. (Original) The apparatus of claim 8, wherein a plurality of spacers having fixed top surfaces support a perimeter portion of the substrate and at least one of the balls is positioned to support a center portion of the substrate.

20. (Previously Presented) The apparatus of claim 8, wherein the balls are coated or plated.

21. (Original) The apparatus of claim 8, wherein the balls are coated or plated chromium, an aluminum alloy, silicon nitride, or tungsten nitride.

22-46. (Cancelled)

47. (Previously Presented) Apparatus for supporting a substrate in a chamber having at least one substrate support member coupled to the chamber, comprising:

a body having a first portion and a second portion, the first portion adapted to interface with the support member;

a socket disposed in the second portion and having a ball support surface; and

a ball rotatably disposed on the ball support surface in the socket, wherein the ball has a surface roughness of 4 micro-inches or smoother, the ball adapted to contact and support a substrate thereon.

48. (Previously Presented) The apparatus of claim 47, wherein the ball is electropolished.

49. (Previously Presented) The apparatus of claim 47, wherein the ball is at least one of coated or plated.

50. (Previously Presented) The apparatus of claim 49, wherein the ball is coated or plated with chromium, an aluminum alloy, silicon nitride, or tungsten nitride.

51. (Previously Presented) The apparatus of claim 47, wherein the ball support surface has a radius greater than a radius of the ball.

52. (Previously Presented) The apparatus of claim 8, wherein the balls are electropolished.

53-58. (Cancelled)

59. (Previously Presented) The apparatus of claim 8, further comprising:

a cassette movably disposed within the chamber, wherein the at least one support member further comprises a plurality of support members coupled to the cassette; and

a cooling plate disposed within the chamber.